

SEMICONDUCTOR DEVICE AND METHOD TO PRODUCE THE SAME

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ABSTRACT OF THE DISCLOSURE

10 The present invention provides a semiconductor  
device, using a bonding wire for linking a semiconductor  
terminal to a connecting terminal for an outside circuit,  
capable of preventing short circuits of the bonding wires  
and excellent in strength and fatigue resistance of the  
bonding joints to cope with the downsizing of the  
terminals and the bonding materials, in which device the  
15 bonding wires are reinforced, partially or wholly, with a  
reinforcing material after bonding work and joint bulbs  
bonded to the terminals using bonding material are  
plated, and a method to produce the same.